



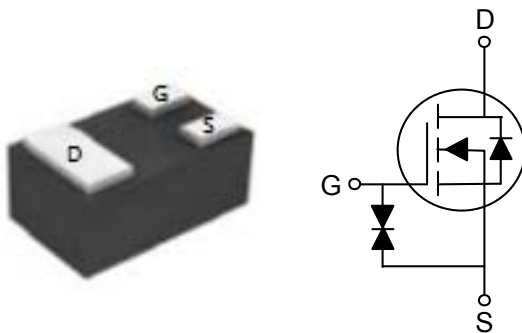
20V N-Channel MOSFETs

**General Description**

The TVMNB220 designed by the trench processing techniques to achieve extremely low on-resistance. And fast switching speed and improved transfer effective.

|                         |                           |                      |
|-------------------------|---------------------------|----------------------|
| <b>BV<sub>DSS</sub></b> | <b>R<sub>DS(ON)</sub></b> | <b>I<sub>D</sub></b> |
| 20 V                    | 220 mΩ                    | 0.7 A                |

SOT-883 Pin Configuration



**Features**

- V<sub>DS</sub>=20V, I<sub>D</sub>=0.7A
- R<sub>DS(ON)</sub>(typ.) < 210mΩ @V<sub>GS</sub>=2.5V
- R<sub>DS(ON)</sub>(typ.) < 180mΩ @V<sub>GS</sub>=4.5V
- Low On-Resistance
- Fast Switching
- Lead-Free, RoHS Compliant

**Applications**

- Load Switch

**Absolute Maximum Ratings T<sub>C</sub>=25°C unless otherwise noted**

| Symbol           | Parameter                            | Rating     | Unit |
|------------------|--------------------------------------|------------|------|
| V <sub>DS</sub>  | Drain-Source Voltage                 | 20         | V    |
| V <sub>GS</sub>  | Gate-Source Voltage                  | ±8         | V    |
| T <sub>J</sub>   | Operating Junction Temperature Range | -50 to 150 | °C   |
| T <sub>STG</sub> | Storage Temperature Range            | -50 to 150 | °C   |
| I <sub>S</sub>   | Diode Continuous Forward Current     | 0.7        | A    |

**Mounted On Large Heat Sink**

| Symbol           | Parameter   | Rating | Unit |
|------------------|---|--------|------|
| I <sub>DM</sub>  | Drain Current - Pulsed (T <sub>C</sub> =25°C)                             | 3      | A    |
| I <sub>D</sub>   | Drain Current - Continuous (V <sub>GS</sub> =10V) (T <sub>C</sub> =25°C)  | 0.7    | A    |
|                  | Drain Current - Continuous (V <sub>GS</sub> =10V) (T <sub>C</sub> =100°C) | 0.5    |      |
| P <sub>D</sub>   | Maximum Power Dissipation (T <sub>C</sub> =25°C)                          | 0.55   | W    |
| R <sub>θJA</sub> | Thermal Resistance Junction to Ambient                                    | 100    | °C/W |



**Electrical Characteristics (T<sub>J</sub>=25°C, unless otherwise noted)**

**Off Characteristics**

| Symbol            | Parameter                      | Conditions   | Min. | Typ. | Max. | Unit |
|-------------------|--------------------------------|--|------|------|------|------|
| BV <sub>DSS</sub> | Drain-Source Breakdown Voltage | V <sub>GS</sub> =0V, I <sub>D</sub> =250uA                       | 20   | ---  | ---  | V    |
| I <sub>DSS</sub>  | Drain-Source Leakage Current   | V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>C</sub> =25°C  | ---  | ---  | 1    | uA   |
|                   |                                | V <sub>DS</sub> =20V, V <sub>GS</sub> =0V, T <sub>C</sub> =125°C | ---  | ---  | 100  | uA   |
| I <sub>GSS</sub>  | Gate-Source Leakage Current    | V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V                        | ---  | ---  | ±100 | nA   |

**On Characteristics**

| Symbol              | Parameter                         | Conditions   | Min. | Typ. | Max. | Unit |
|---------------------|-----------------------------------|--|------|------|------|------|
| R <sub>DS(ON)</sub> | Static Drain-Source On-Resistance | V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.5A              | ---  | 180  | 220  | mΩ   |
|                     |                                   | V <sub>GS</sub> =2.5V, I <sub>D</sub> =0.3A              | ---  | 210  | 260  |      |
| V <sub>GS(th)</sub> | Gate Threshold Voltage            | V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA | 0.4  | 0.8  | 1.2  | V    |

**Dynamic and switching Characteristics**

| Symbol              | Parameter                    | Conditions  | Min. | Typ. | Max. | Unit |
|---------------------|------------------------------|---|------|------|------|------|
| Q <sub>g</sub>      | Total Gate Charge            | V <sub>DS</sub> =10V, V <sub>GS</sub> =4.5V, I <sub>D</sub> =0.5A   | ---  | 1.1  | ---  | nC   |
| Q <sub>gs</sub>     | Gate-Source Charge           |   | ---  | 0.3  | ---  |      |
| Q <sub>gd</sub>     | Gate-Drain Charge            |   | ---  | 0.2  | ---  |      |
| T <sub>d(on)</sub>  | Turn-On Delay Time           | V <sub>DD</sub> =10V, V <sub>GS</sub> =4.5V, R <sub>G</sub> =6Ω, I <sub>D</sub> =0.3A, R <sub>L</sub> =5Ω | ---  | 2.2  | ---  | nS   |
| T <sub>r</sub>      | Rise Time                    |   | ---  | 4    | ---  |      |
| T <sub>d(off)</sub> | Turn-Off Delay Time          |   | ---  | 18   | ---  |      |
| T <sub>f</sub>      | Fall Time                    |   | ---  | 9    | ---  |      |
| C <sub>ISS</sub>    | Input Capacitance            | V <sub>DS</sub> =10V, V <sub>GS</sub> =0V, F=1MHz   | ---  | 40   | ---  | pF   |
| C <sub>OSS</sub>    | Output Capacitance           |   | ---  | 15   | ---  |      |
| C <sub>RSS</sub>    | Reverse Transfer Capacitance |   | ---  | 6.5  | ---  |      |

**Drain-Source Diode Characteristics and Ratings**

| Symbol          | Parameter                                | Conditions   | Min. | Typ. | Max. | Unit |
|-----------------|--|--|------|------|------|------|
| I <sub>SD</sub> | Source-Drain Current (Body Diode)        | T <sub>C</sub> =25°C   | ---  | ---  | 0.5  | A    |
| I <sub>SM</sub> | Pulsed Source-Drain Current (Body Diode) |  | ---  | ---  | 3    | A    |
| V <sub>SD</sub> | Diode Forward Voltage                    | V <sub>GS</sub> =0V, I <sub>SD</sub> =0.5A, T <sub>J</sub> =25°C | ---  | 0.75 | 1.2  | V    |



Characteristics Curves

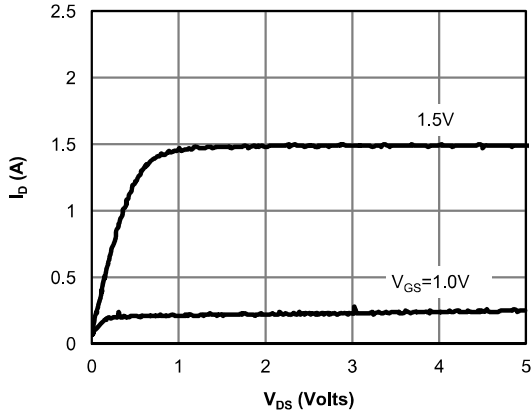


Figure 1: On-Region Characteristics

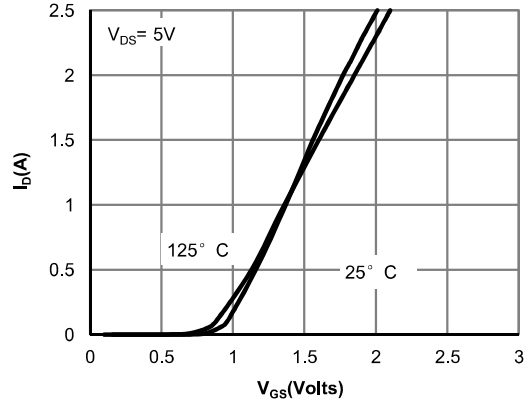


Figure 2: Transfer Characteristics

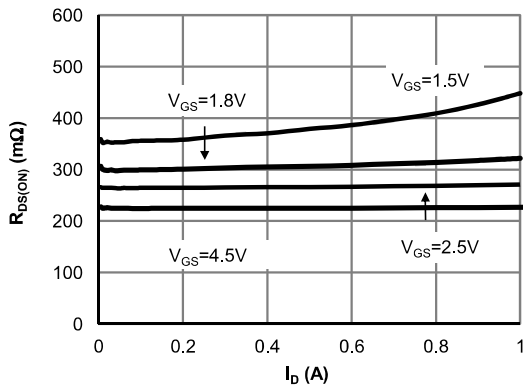


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

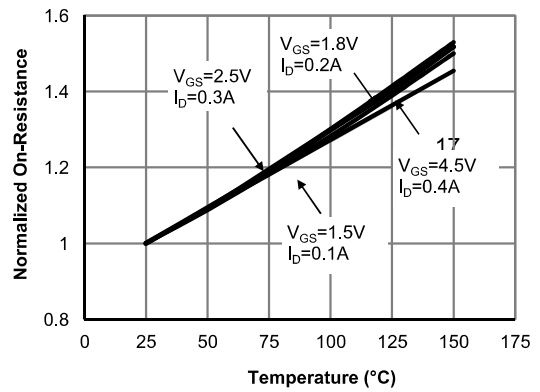


Figure 4: On-Resistance vs. Junction Temperature

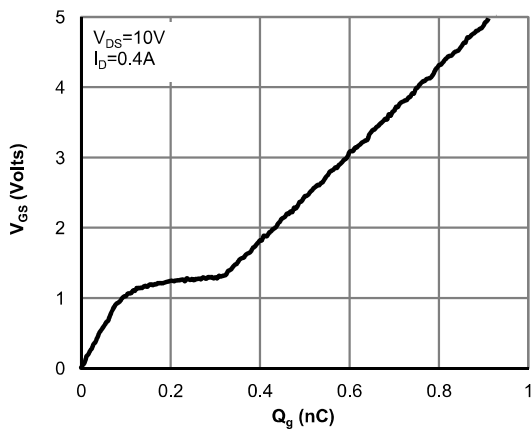


Figure 5: Gate-Charge Characteristics

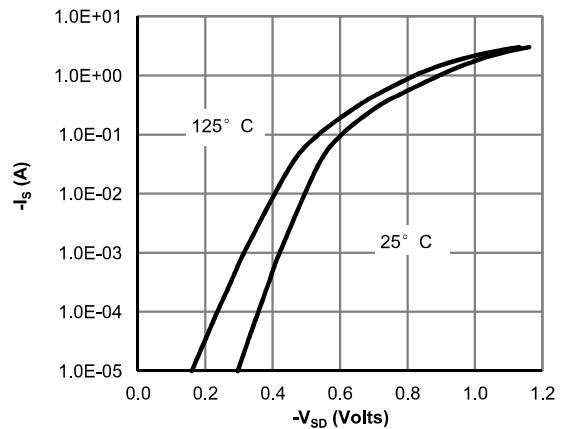


Figure 6: Body-Diode Characteristics



Characteristics Curves

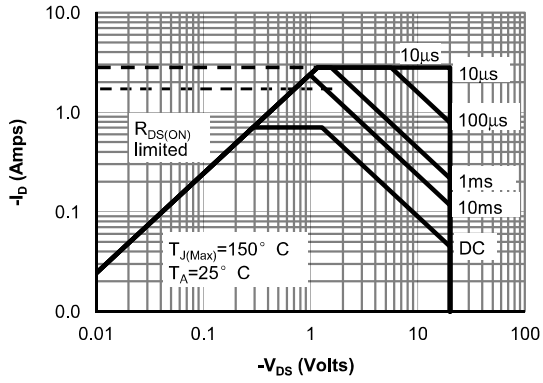


Figure 7: Maximum Forward Biased Safe Operating Area

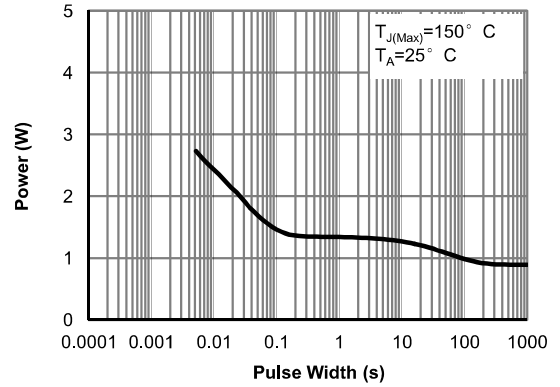


Figure 8: Single Pulse Power Rating Junction-to-Ambient

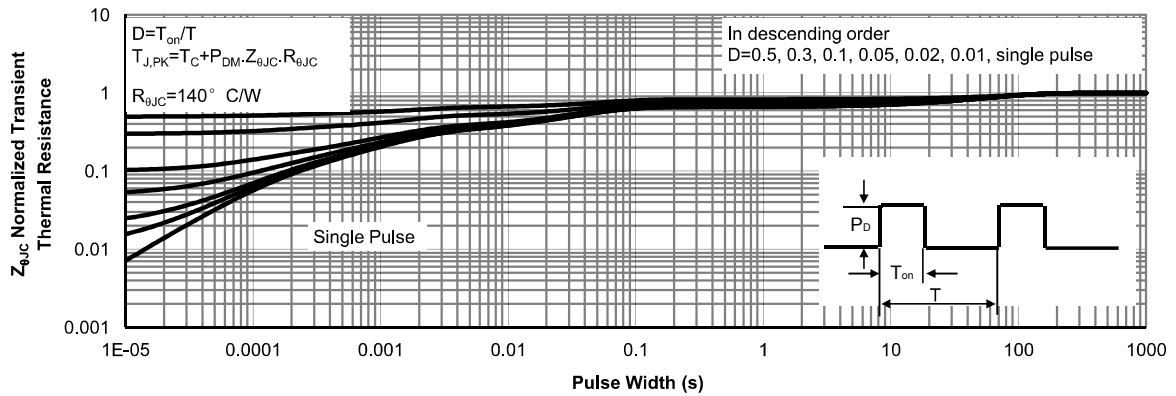


Figure 9: Normalized Maximum Transient Thermal Impedance



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